

NT-H1 3.5g SW Edition

Noctua NT-H1 3.5g SW Edition

Thermal compound



LOGISTIC DATA

Product name
Noctua NT-H1 3.5g SW Edition
EAN
9010018201345
UPC
841501121340
Packaging dimensions (HxWxD)
140x85x16 mm
Weight incl. packaging
46 g
Warranty
-
Packaging unit
80 pcs
Packaging dimensions / unit (HxWxD)
361x306x206 mm
Weight incl. packaging / unit
4.20 kg

SCOPE OF DELIVERY

1x NT-H1 3.5g high-grade thermal compound
Spatula for spreading
3x NA-CW1 cleaning wipes

Noctua's NT-H1 is a renowned hybrid thermal compound that has received more than 150 awards and recommendations from international hardware websites and magazines. Thanks to its excellent performance, exceptional ease of use and outstanding long-term stability, it has become an established favourite among overclockers and enthusiast users worldwide. Whether it's air- or water-based cooling, CPU or GPU applications, overclocking or silent systems: NT-H1 is a proven premium paste that's guaranteed to deliver great results. The SW (Spatula & Wipes) Edition includes a spatula for users who prefer to manually spread the paste before installing the heatsink as well as three NA-CW1 cleaning wipes for pre-application cleaning and easy removal.

Award-winning performance

Bundled with Noctua's premium-grade CPU coolers since 2007, NT-H1 has proven its excellent performance in countless of tests and reviews. Chosen again and again by overclockers and hardware enthusiasts around the globe, it has established itself as a benchmark for premium-quality thermal interface materials (TIMs).

SW (Spatula & Wipes) Edition

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Not electrically conductive, non-corroding

While some high-end thermal compounds and pads are risky to use due to their electrical conductivity or corroding properties, there's no risk of short-circuits with NT-H1 and it's completely safe to use with any type of CPU cooler, regardless of whether it's made from copper or aluminium and whether it's nickel-plated or not.

Excellent long-term stability

NT-H1's unique formula is highly stable over time, even after longer periods of usage. It can be stored at room temperature for at least 3 years and due to the compound's exceptional curing, bleeding, dry-out and thermal cycling characteristics, it can be used on the CPU for 5 years or more.

No break-in or burn-in required

Some thermal compounds need a longer break-in period or cure time until they reach their full performance and some thermal pads must undergo a dedicated burn-in process. By contrast, NT-H1 is ready to go right away and doesn't require any special preparations.

3.5g package for 3-20 applications

Sufficient for around 3-20 applications (depending on the size of the CPU or GPU, e.g. around 3 applications for large CPUs such as TR4 and around 20 for small CPUs such as LGA1151), the classic 3.5g packaging size is ideal for most users who only install coolers every now and then.

Specifications NT-H1 3.5g

Weight	3.5 g
Volume	1.4 ml
Density	2.49 g/cm ³
Colour	grey
Recommended storage time (before use)	up to 3 years
Recommended usage time (on the CPU)	up to 5 years
Recommended storage temperature	room temperature
Operating temperature	-50 to 110 °C



Caution: Do not ingest. Seek medical advice immediately if ingested. Keep away from children and pets. Avoid skin or eye contact.